

SOT1461-1

WLCSP13, wafer level chip-size package; 13 bumps, 0.4 mm pitch, 2.74 mm x 2.80 mm x 0.38 mm body

23 February 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP13
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	8-8-2016
Manufacturer package code	SOT1461

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.77	-	2.8	2.83	mm
E	package width	2.71	-	2.74	2.77	mm
A	seated height	0.34	-	0.38	0.42	mm
A ₂	package height	-	-	-	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	13	-	



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2. Package outline

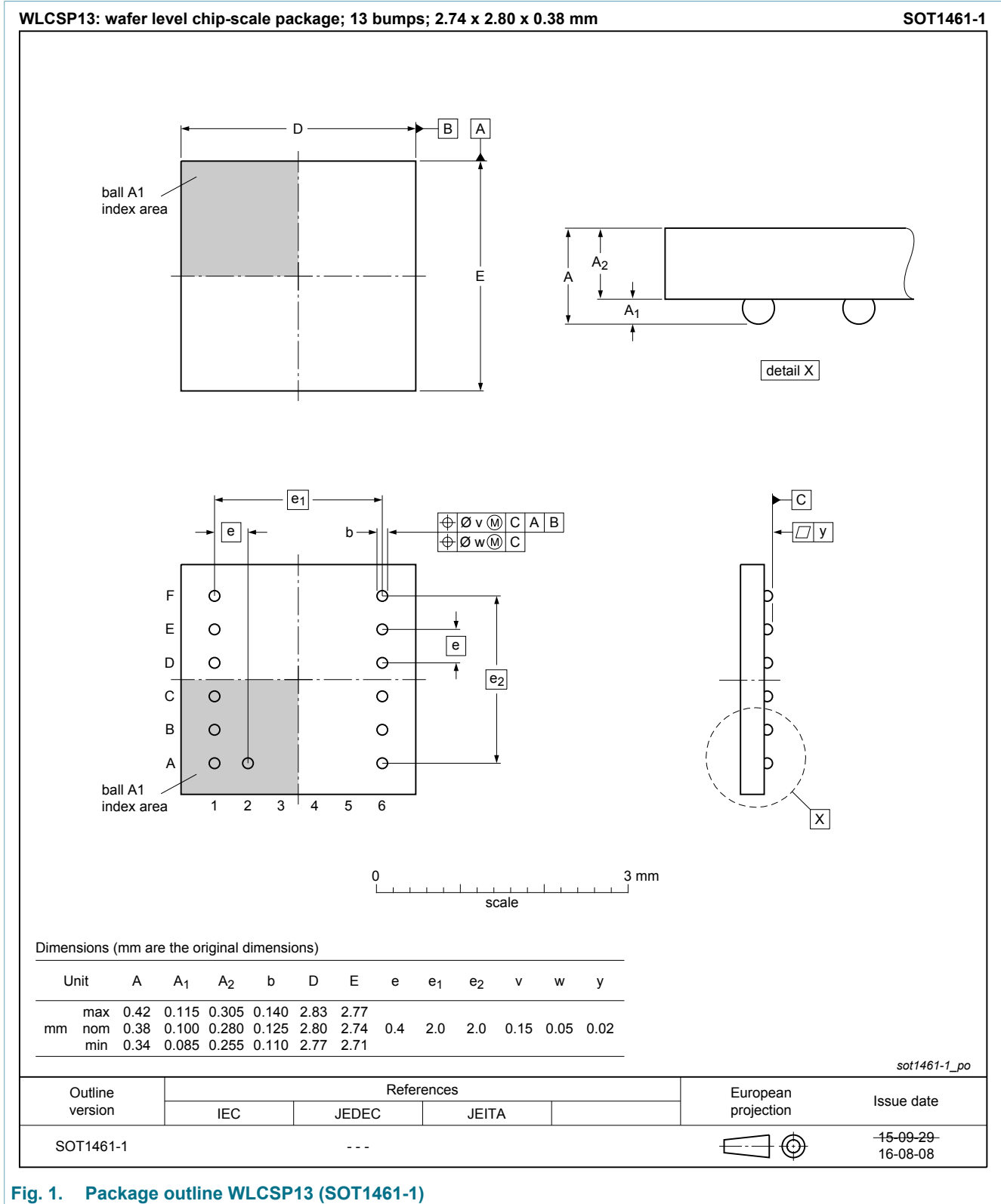


Fig. 1. Package outline WLCSP13 (SOT1461-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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